

MICRON.086DV1



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Brenton L. Dickey  
Appl. No. : 09/858,118  
Filed : May 15, 2001  
For : SUBSTRATE FILM  
STRUCTURE  
Examiner : James M. Mitchell

Group Art Unit 2827

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: United States Patent and Trademark Office, P.O. Box 2327, Arlington, VA 22202, on

August 26, 2002

(Date)

*John R. King*  
John R. King, Reg. No. 34,362

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RESPONSE TO OFFICE ACTION DATED APRIL 25, 2002

United States Patent and Trademark Office  
P.O. Box 2327  
Arlington, VA 22202

Dear Sir:

In response to the Office Action mailed April 25, 2002, Applicant respectfully submits the following amendments and remarks in connection with the above-captioned application.

**AMENDMENT**

IN THE TITLE:

Please amend the title from "SUBSTRATE FILM STRUCTURE" to --METHOD OF SUPPORTING A SUBSTRATE FILM--.

IN THE SPECIFICATION:

On page 1, immediately after the title, please insert:

Related Application

This application is a divisional of U.S. Application No. 09/389,720, filed September 3, 1999.

IN THE CLAIMS:

Please cancel Claims 35-58 without prejudice.

Please add new Claims 59-69 as follows:

59. (NEW) A method of manufacturing an assembly comprising:  
combining layers of solder resist with a polyimide film to construct side bars;  
connecting said side bars to a substrate film;

09/03/2002 FORWARDED 00000016-09858118

01 FC:118

-400.00 DP

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